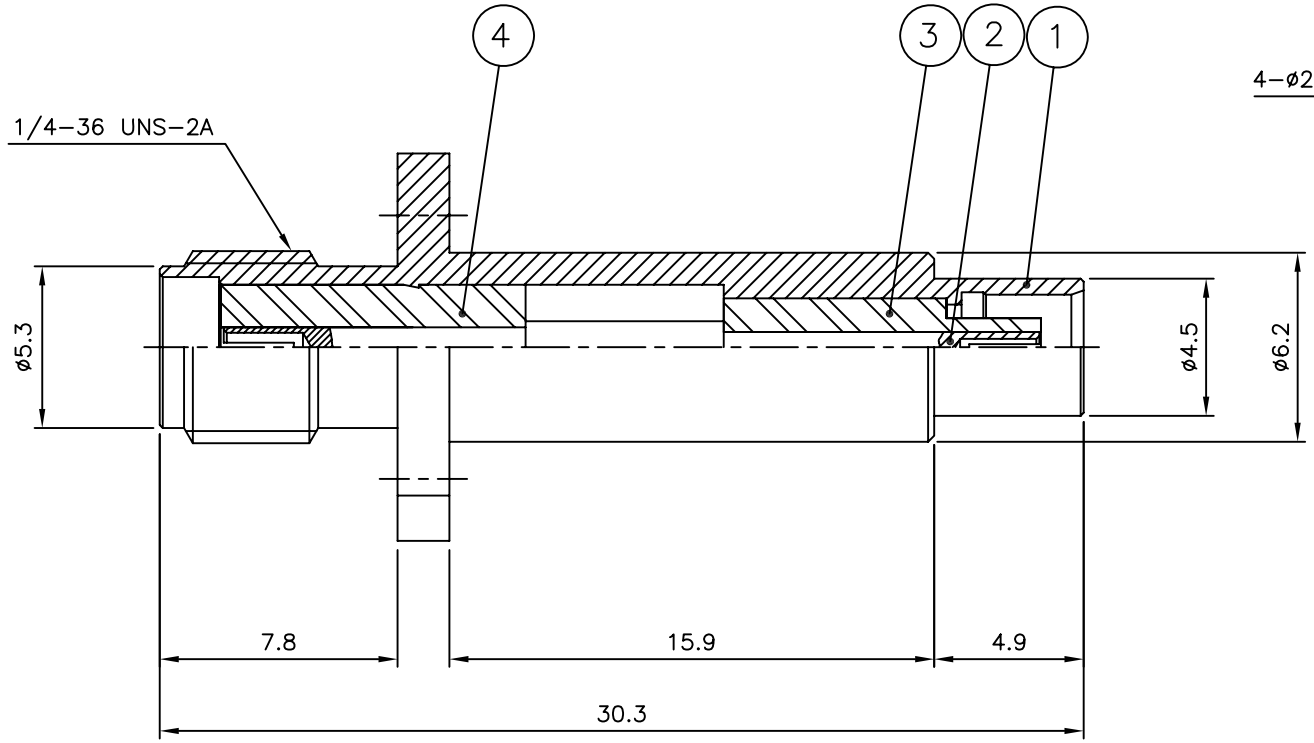
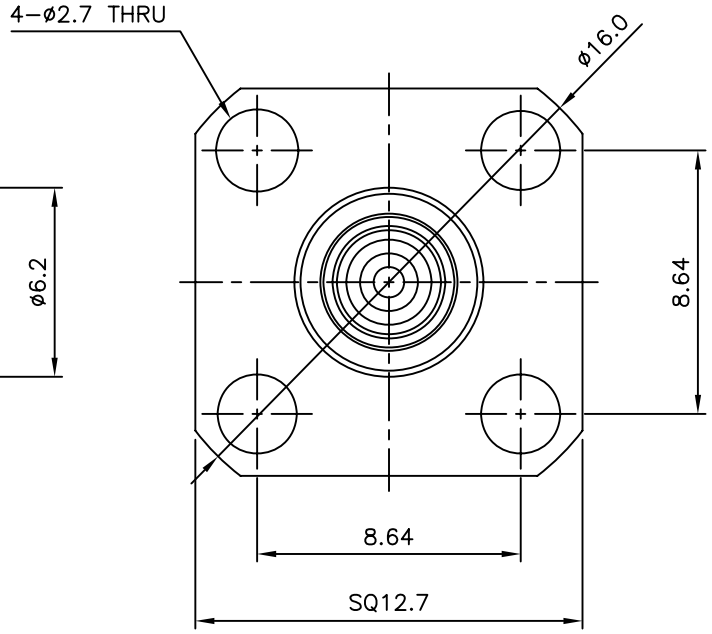
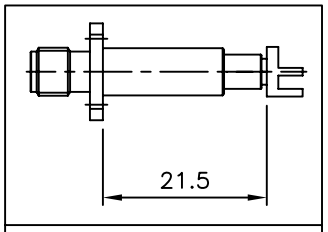
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	G.Y.KIM	I.C.KIM	2016.11.11.







상대물 CN03294-7/1 과 체결 치수

NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
4	INSULATOR	1	TEFLON		DIN01014-N/1
3	INSULATOR	1	TEFLON		DIN01649-N/2
2	CONTACT	1	BeCu C17300	Gold Plate	DAC03263-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DAD00325-5/1

*조립방법

1. ②번 PIN과 ③번 TEFLON을 손으로 결합한다.
2. ①번 BODY에 ②③번 조립품을 가조립한다.
3. ①번 BODY에 ④번 TEFLON 가조립 후 PIN 높이 JIG를 이용하여 조립

TOLERANCE	Decimal ±0.1	DATE	2016. 11. 11.
	Angle ±1°	APPROVED BY	I.C.KIM
MATERIAL		CHECKED BY	C.K.KIM
		DRAWN BY	G.Y.KIM
FINISH		SCALE 4/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.

RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
Fax : 82-32-347-8017

TITLE MCX50 (J) SMA50 (J) 4H ADAPTOR

A4

DWG NO. AD00593-7/1

REVISION I R

SHEET 1 of 1